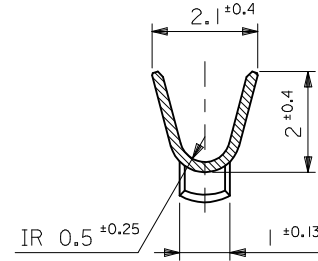
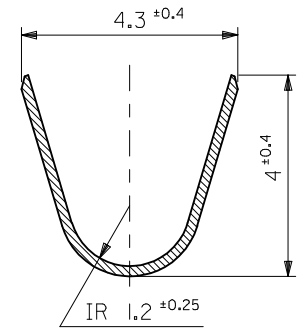


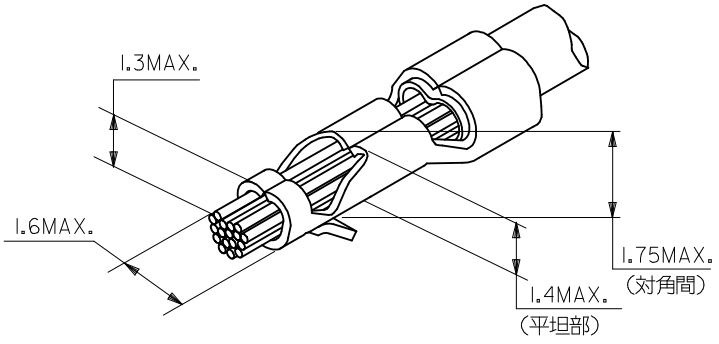
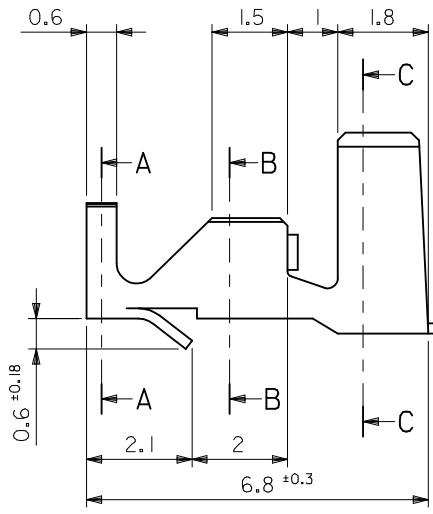
SECT. A-A



SECT. B-B



SECT. C-C



圧着外観図  
OUTSIDE VIEW OF CRIMP

NOTES

- 推奨プリント基板孔径:  $\phi 1.8^{+0.1}$   
RECOMMENDED P.C.B. HOLES:  $\phi 1.8^{+0.1}$
- 推奨プリント基板厚:  $t1.57^{+0.2}$   
RECOMMENDED P.C.B. THICKNESS:  $1.57^{+0.2}$
- 材料の厚み: 0.203  
MATERIAL THICKNESS: 0.203

TIN-LEAD(90-10) 3.8 $\mu$ m MIN. OVER NICKEL 1.3 $\mu$ m MIN.	PHOSPHOR BRONZE	CHAIN	39-00-0277	5298PBPT
TIN 0.9 $\mu$ m MIN. REFLOW TREATMENT (PRE-PLATED)	PHOSPHOR BRONZE	CHAIN	39-00-0230	5298PBT
TIN 0.9 $\mu$ m MIN. OVER COPPER 0.5 $\mu$ m MIN. (PRE-PLATED)	BRASS	CHAIN	08-70-0106	5298T
PLATING		MATERIAL	FORM	EDP NO.
				ENG. NO.

材料 MATERIAL	SEE TABLE & NOTE
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	AWG #18-22
被覆外径 INS. RANGE	$\phi 1.7-3.05$

REVISED	EC NO. J2017-0224	DRW: NISHIKAWA 2016/10/12	CHK: K.TAKAHASHI 2016/10/12	APP: M.SASAO 2016/10/14
DESCRIPTION				
REV				

GENERAL TOLERANCES (UNLESS SPECIFIED)		
0.25 UNDER	±	
0.25 OVER	0.5 UNDER	±
0.5 OVER	1.0 UNDER	±
10 OVER	10 UNDER	±0.2
30 OVER	30 UNDER	±0.25
ANGULAR	±3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY			METRIC	
DRAWN BY	DATE	TITLE		
H.HIRAMOTO	'91/09/05	LOW PROFILE PC BOARD CRIMP PIN		
CHECKED BY	DATE			
H.HIRAMOTO	'93/07/06			
APPROVED BY	DATE			
M.FUKUSHIMA	'93/07/06	MATERIAL NO.		
SEE TABLE		SD-5298-001		

DRAWN BY		DATE	TITLE	
H.HIRAMOTO		'91/09/05	LOW PROFILE PC BOARD CRIMP PIN	
CHECKED BY		DATE		
H.HIRAMOTO		'93/07/06		
APPROVED BY		DATE		
M.FUKUSHIMA		'93/07/06	MATERIAL NO.	
SEE TABLE		SD-5298-001		
SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
A3				

单击下面可查看定价，库存，交付和生命周期等信息

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